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### TOSHIBA 8GB, 16GB, 32GB, 64GB, 128GB eMMC PCN/EOL Announcement

It is Toshiba Memory Corporation's (TMC) objective to remain a technology leader in the semiconductor industry. As a result, TMC is announcing PCNs for 8-128GB eMMC density to enable better support/longevity.

TMC will change the eMMC controller wafer fabrication site from Sony Semiconductor Manufacturing Corporation (SCK) to Taiwan Semiconductor Manufacturing Limited (TSMC) for 15nm based eMMC for 8-32GB densities, and will introduce BiCS FLASH™ 3D eMMC for 16-128GB densities.

#### **AFFECTED PRODUCTS/SCHEDULE OF EOL and SUGGESTED REPLACEMENT OPTIONS:**

				DISCONTINUED PRODUCTS	
Temp.	Dens.	Spec.	15nm	P/N	*LTB & LTS for SCK
-40degC to +85degC	8GB		15nm	THGBMHG6C1LBAW6/THGBMHG6C1LBAWL	End/Jun/2019 & End/Sep/2019
	16GB		15nm	THGBMHG7C2LBAW7/THGBMHG7C2LBAWR	
	32GB		15nm	THGBMHG8C4LBAW7/THGBMHG8C4LBAWR	
	64GB		15nm	THGBMHG9C8LBAW8/THGBMHG9C8LBAWG	
-40degC to +105degC	8GB		15nm	THGBMHG6C1LBAU6	
	16GB		15nm	THGBMHG7C2LBAU7	
	32GB		15nm	THGBMHG8C4LBAU7	
	64GB		15nm	THGBMHG9C8LBAU8	
-25degC to +85degC	8GB	NCQ**	15nm	THGBMFG6C1LBAIL	
		CQ	15nm	THGBMHG6C1LBAIL	
	16GB	NCQ**	15nm	THGBMFG7C1LBAIL	
		Premium	15nm	THGBMHG7C1LBAIL	
	32GB	Supreme	15nm	THGBMHG7C2LBAIL	
		NCQ**	15nm	THGBMFG8C2LBAIL	
		Premium	15nm	THGBMHG8C2LBAIL	
	64GB	Supreme	15nm	THGBMHG8C4LBAIR	
		Premium	15nm	THGBMGG9U4LBAIR	
	128GB	Supreme	15nm	THGBMHG9C4LBAIR	End/Jul/2019 & End/Oct/2019
Premium		15nm	THGBMGT0U8LBAIG		
	Supreme	15nm	THGBMHT0C8LBAIG	End/Aug/2019 & End/Nov/2019	

				SUGGESTED REPLACEMENT PRODUCTS	
Temp.	Dens.	Spec.	15nm/BiCS	P/N	CS/Data sheet for TSMC
-40degC to +105degC	8GB		15nm	THGBMJG6C1LBAU7	End/Mar/2019
	16GB		15nm	THGBMJG7C2LBAU8	End/Mar/2019
	32GB		15nm	THGBMJG8C4LBAU8	End/Mar/2019
	64GB		15nm	THGBMJG9C8LBAU8	End/Mar/2019
-25degC to +85degC	8GB	CO	15nm	THGBMJG6C1LBAIL	End/Mar/2019
		Premium	15nm	THGBMJG7C1LBAIL	End/Mar/2019
	32GB		BiCS FLASH	THGAMRG7T13BAIL	End/Mar/2019
		Premium	15nm	THGBMJG8C2LBAIL	End/Mar/2019
	64GB		BiCS FLASH	THGAMRG8T13BAIL	End/Mar/2019
			BiCS FLASH	THGAMRG9T23BAIL	End/Apr/2019
128GB		BiCS FLASH	THGAMRT0T43BAIR	End/May/2019	

Note: \*LTB = Last Time Buy Order Issue Date. LTS = Last Time Shipment Date.

Note: \*\*NCQ = non-command queuing. This feature CQ (command queuing) was added after initial part introduction in the market

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### **Additional Comments for Consumer Temperature eMMC (-25C to +85C):**

We expect 15nm eMMC parts with controller fabricated at TSMC to be drop in replacement to SCK parts for 8GB, 16GB Premium and 32GB Premium, though we recommend customer validation.

For 16GB and 32GB density, there are two replacement options:

16/32GB 15nm Premium

16/32GB BiCS FLASH 3D memory\*

\*16/32GB with BiCS FLASH 3D is recommended over 15nm for better support flexibility/longevity.

For 64GB and 128GB eMMC, there is one replacement option, which will provide better support flexibility and longevity:

64GB/128GB BiCS FLASH 3D memory

### **Additional Comments for Industrial/Extended Temperature eMMC (-40C to +85C/105C):**

For 8GB to 64GB industrial/extended temperature eMMC, we are consolidating our lineup to one solution that encompasses the extended temperature range:

8GB – 64GB (-40C to +105C)

Thank you for your cooperation in the implementation of this change.

Toshiba Memory America